

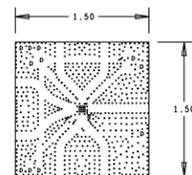
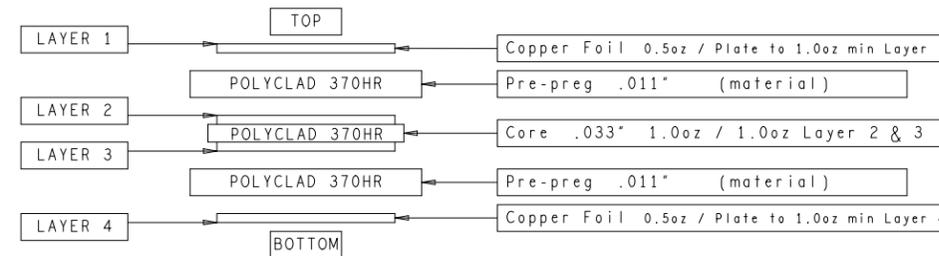
UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.  
 NOTES PRECEDED BY AN UNMARKED "□" ARE NOT APPLICABLE.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

- APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.  
 IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.  
 IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.  
 IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- HOLE SIZE APPLIES AFTER PLATING. TOLERANCE TO BE +/- .003.
- REGISTRATION TOLERANCE: ARTWORK +/- .002  
 ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.  
 FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.  
 MATERIAL:  SINGLE SIDED,  DOUBLE SIDED,  MULTI-LAYER (SEE DETAIL "A")  
 SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 +/- 10%
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT).  
 COLOR=RED (0.001 TO 0.002" THICK OVER METAL).
- SILKSCREEN  TOP SIDE  BOTH SIDES. USING  YELLOW  WHITE NPI LEADFREE.  
 REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH.  
 MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

- TOP SIDE TRACES THAT ARE 18.0 mils SHALL BE 50ohms SINGLE ENDED, +/- 10% TOLERANCE.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 10 MILS.  
 MINIMUM COPPER SPACING IS: 5 MILS.
- SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.
- ALL THRU HOLE VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY.  
 FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANOR.
- GROUND ETCH TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.
- NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.
- FINISHED BOARD MUST BE RoHS COMPLIANT AND SURVIVE A LEAD FREE ASSEMBLY,  
 MAXIMUM REFLOW OF 260 DEGREES C (6 PASSES).
- BOARD TO BE PANELIZED FOR ASSEMBLY.
- HOLE SIZE APPLIES AFTER PLATING. TOLERANCE TO +/- .003/- .010.

DETAIL "A"



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	10.0	PLATED	699
◦	38.0	PLATED	6
◦	40.0	PLATED	5

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UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING	
MATERIAL SEE NOTE 5	DRAWN	P. LARSON	TRF3705	
	ENGR	C. SIPP		
FINISH SEE NOTES 7, 8, 9			SIZE	REV.
DO NOT SCALE DRAWING			B	B
			SCALE	SHEET 1 OF 1
			NONE	